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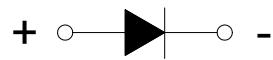
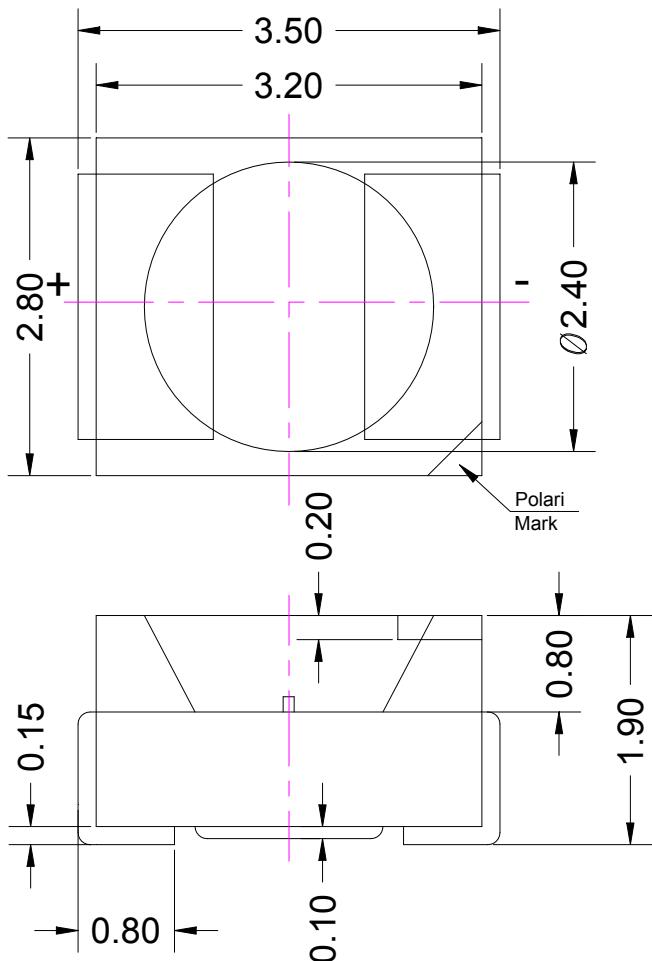
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Wen Li	Fang Yang	Jiang Yang	Fang Wang




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Tolerance: 0.25(0.01)



Uni mm

Color Pre Green

Len -color Water clear

Emitting Material InGaN

Drawing boliation



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3 Charac eri ic

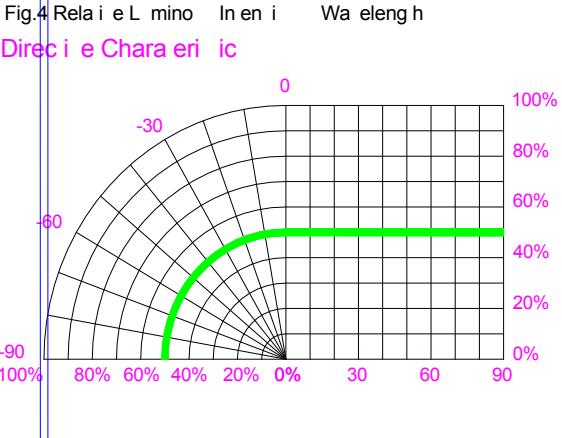
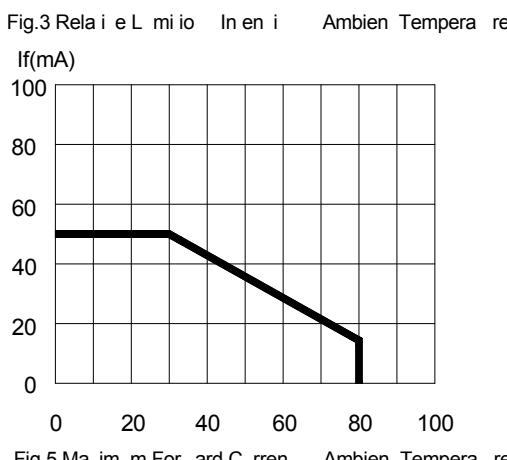
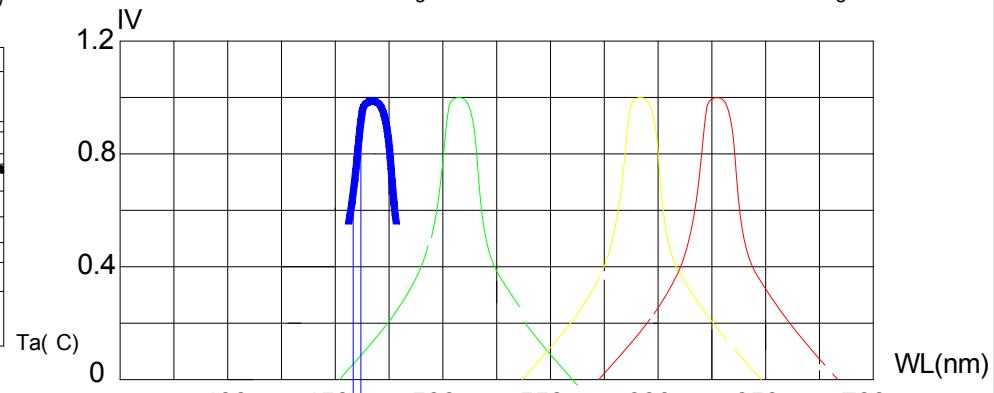
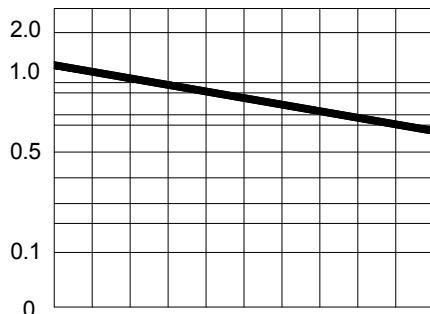
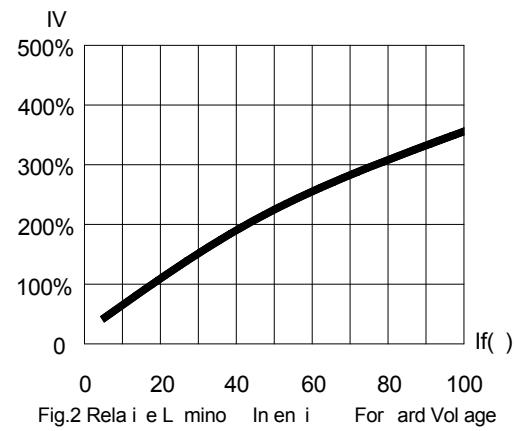
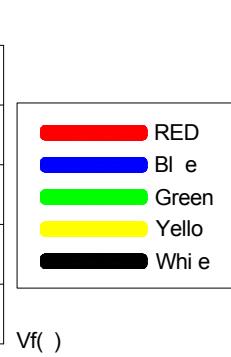
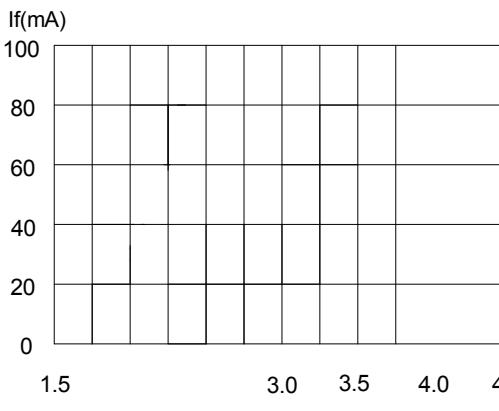
Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	Tg	-30 +80	C			
Peak holding current 1/8 d f=1KH	Ifp	125	mA			
Wavelength at peak emission	If=20mA	peak	515	520	525	nm
Spectral half bandwidth	If=20mA			10		
Forward voltage	If=20mA	Vf	3.0		3.6	V
Luminous intensity	If=20mA	I	800	1100	1300	mcd



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Vie ing angle a 50% IV	If=10mA		--	120	--	Deg
Re er e c ren	Vr=5V	Ir	--	--	5	A
U ef I life	-	IF=20mA	100000			H

Typical Electrical/Optical Characteristics Curve  
(Ta=25 Unless Otherwise Noted)





1	Tin-plated e	Temp 260 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temperature	High temp. +85 30min or 5min or -55 30min	50 bo	76 PCS	0/1
3	Heating padding e	High temp. +100 30min To 10 sec or -10 30min	50 bo	76 PCS	0/1
4	High voltage emp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low voltage emp.	-55	1000 Hr.	76 PCS	0/1
6	Lift pane	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Temperature high emp.& high humidity	85 /85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: heat Iron (max 30W) until temperature higher than 300°C, soldering time 3 second, soldering position minim 2mm from board.

ii Dip Soldering: Max temperature in 260°C, time 5s, heating position minim 2mm from board.

i Brackets must be bent only if 2mm from colloid.

ii Brackets must be finished before professional.

iii Brackets must be finished before soldering.

i Brackets must hold a hole where the connection between the pin, the distance gap of lead and the circuit board.

i. I should be paying attention to the ordering of all the dice in case of wrong polarity. The dice can be too close to the heat component, working condition can affect the limit.

ii. I should not assemble LED when the leads are deformed.

iii. When decide to assemble in hole, accurate account the size of hole and hole distance of the line base

i. Suggesting hard heating positioning

. I should avoid any kind of shake or force on LED, before the soldering temperature return normal.

I should be careful. When clean the board with chemical. Some chemicals may bring damage to the surface, and bring color fading, such as Trichloroethylene, Acetone. Should use ethanol or acetone, dip for no more than 3 minutes under the normal temperature.



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